

Microelectronic failure analysis: desk reference, 2001 supplement

Deskripsi Lengkap: <https://lib.ui.ac.id/detail?id=20442592&lokasi=lokal>

Abstrak

Contents :

- Microelectronics failure analysis desk reference, 2001 supplement
- Preface
- Microelectronic Failure Analysis Desk Reference 2001 Supplement
- FIB Backside Isolation Techniques
- The SEM Lab, From Laboratory Logistics to Final Sample Preparation Techniques for SEM Analysis of Semiconductors
- Cross Sectioning with a Pivoting Sample Block
- Focused Ion Beam Cross Sectioning as a Compliment or an Alternative to Conventional Mechanical Sectioning Techniques
- Alternatives to Cross-Sectional Sample Preparation for Package and Board-Level Failure Analysis
- Automation To Boost Productivity And Increase Repeatability: (A Sampling of Available Tools and Vendors)
- Multi-Functional, Semi-Automatic Sample Preparation for Failure Analysis
- SMPT©-Sub-Micron Polishing Technology For Automated Sample Preparation
- Automated Techniques For SEM And TEM Sample Preparation
- Sample Preparation Techniques for Site-Specific Cross-Sectional Analysis of High-Aspect-Ratio FIB Repair Sites
- Deprocessing, Cross-Sectioning and FIB Circuit Modification of Parts Having Copper Metallization
- Scanning Capacitance Microscopy of Junction and Non-Junction Samples
- Electrical Probing of Deep Sub-Micron Integrated Circuits Using Scanning Probe Techniques
- Application of Tunneling Atomic Force Microscopy (TUNA) to Failure Analysis
- GoFATA: Glossary of Failure Analysis Tool Acronyms
- ISTFA Subject Index